

ESDULC5V0D5B

Description

ESDULC5V0D5B is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium.

Features

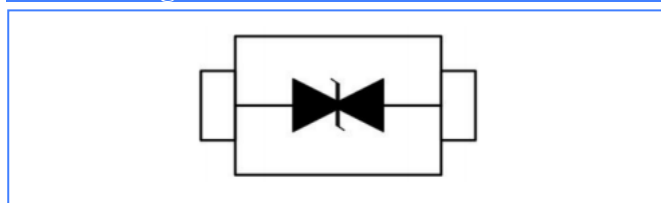
- Package: SOD-523
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- Response Time is Typically < 1 ns
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 20\text{kV}$
 - Contact discharge: $\pm 15\text{kV}$
 - IEC61000-4-5 (Lightning) 4A (8/20 μs)
 - IEC61000-4-4 (EFT) 40A (5/50ns)



Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Circuit Diagram



Absolute Ratings

Tamb=25°C unless otherwise specified

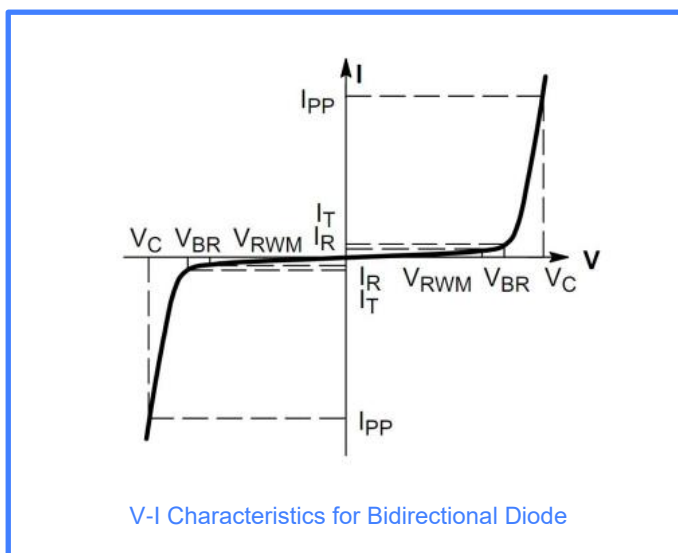
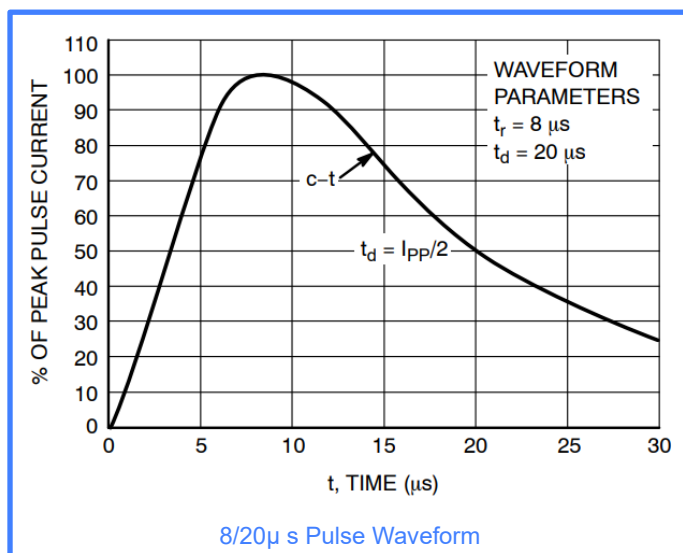
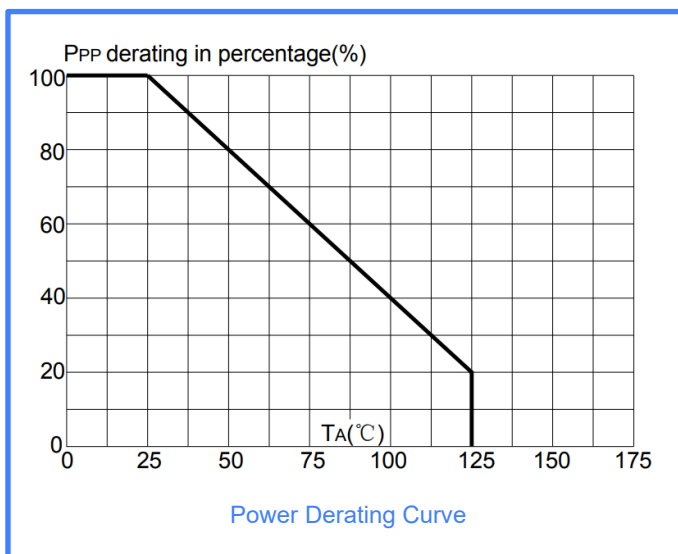
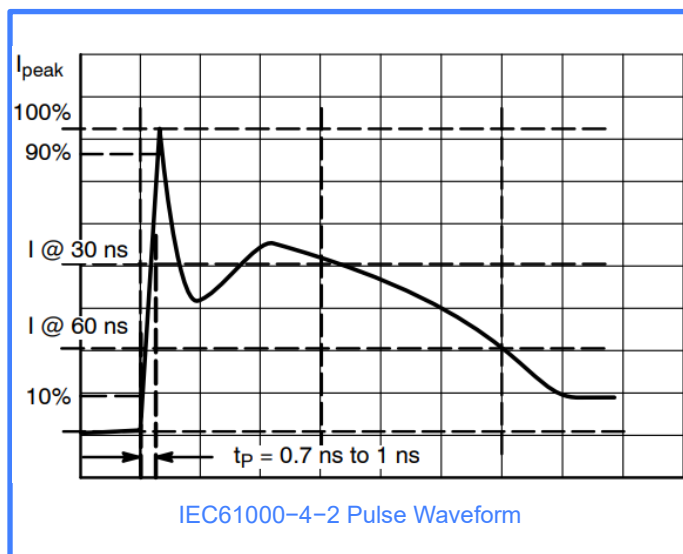
Parameter	Symbol	Value	Unit
Maximum Reverse Peak Pulse Current(8/20 μs)	I_{PP}	4	A
ESD per IEC 61000-4-2 (Air)	V_{ESD}	± 20	KV
ESD per IEC 61000-4-2 (Contact)		± 15	
Storage Temperature Range	T_{STJ}	-55 to +150	°C
Operating Temperature Range	T_J	-40 to +125	°C
Lead Soldering Temperature	T_L	260 (10 sec)	°C

Electrical Characteristics

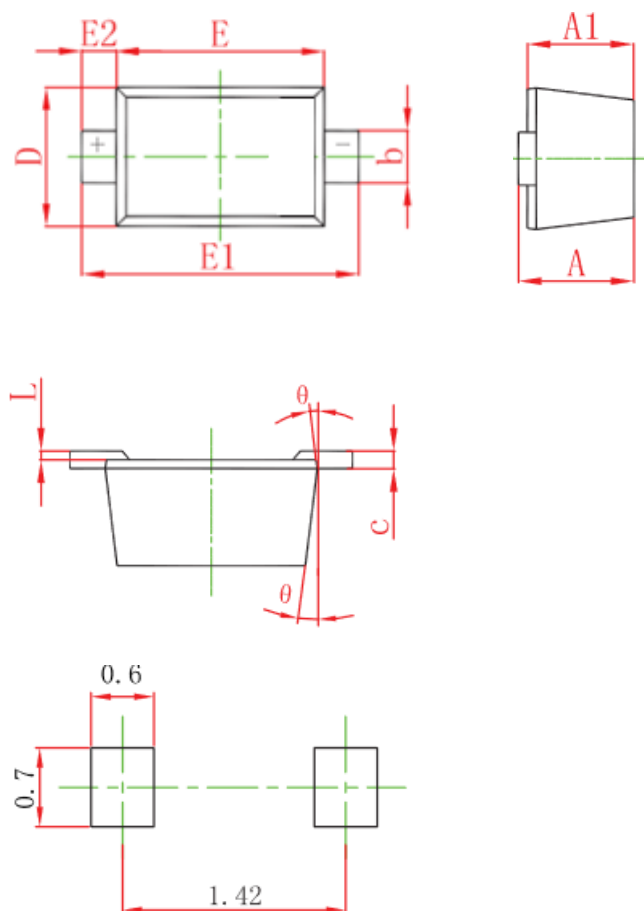
TA=25°C unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{RWM}	Reverse Working Peak Voltage	-			5.0	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	6.5	7.5	9.0	V
I_R	Reverse Current	$V_{RWM} = 5\text{V}$			0.1	μA
V_C	Clamping Voltage	$I_{PP}=1\text{A}$, $t_P = 8/20\mu\text{s}$			9	V
V_C	Clamping Voltage	$I_{PP}=4\text{A}$, $t_P = 8/20\mu\text{s}$			14	V
C_D	Diode Capacitance	$V_R = 0\text{V}$, $f = 1\text{MHz}$		0.5	0.6	pF

Characteristic Curves



SOD523 Package Outline & Dimensions



Symbol	Dimensions in mm	
	min	max
A	0.530	0.730
A1	0.500	0.700
b	0.280	0.380
c	0.080	0.150
D	0.750	0.850
E	1.100	1.300
E1	1.500	1.700
E2	0.200REF	
L	0.010	0.070
θ	7° REF	

Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.